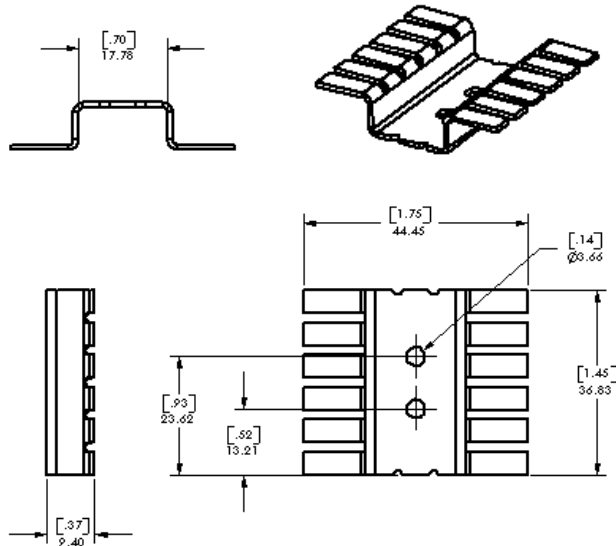
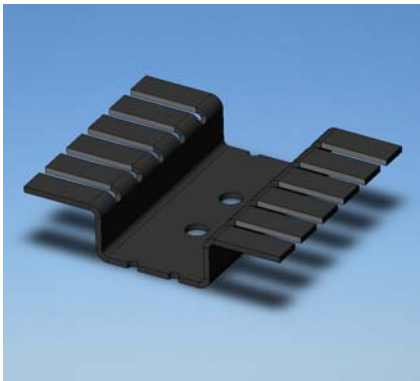


Board Level Heat Sinks



ThermaFlo

P/N: 824302B00000



PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 36.8 x 44.5 x 9.4 mm
- Material: Aluminum, 1.0 mm Thick
- Weight: 5.0 grams
- Type: Stamped
- PCB Mounting: Device Leads
- Finish: Black Anodized
- Package: Bulk
- Accessories: Hardware & Thermal Interface Material

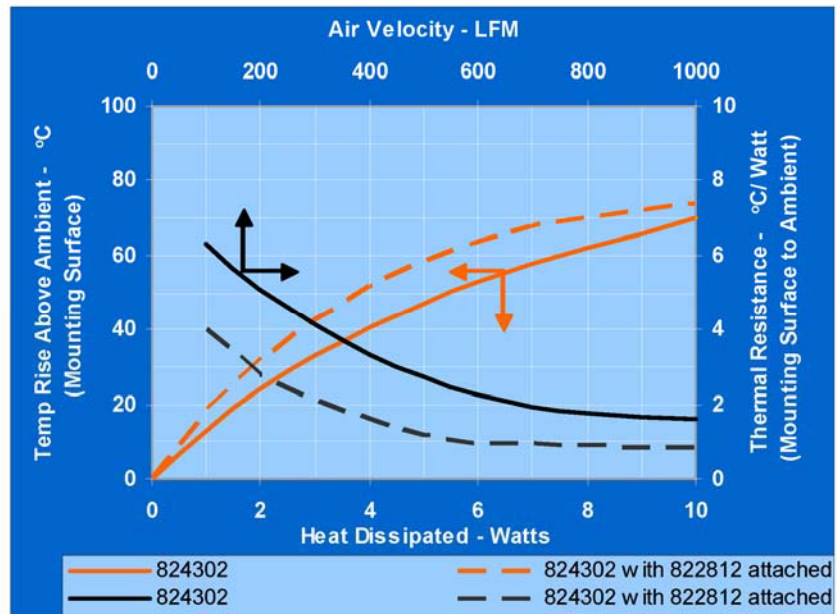
FEATURES & BENEFITS

- Multiple Holes for Device Attachment
- Dual Device Cooling System
- Mates with PN 822812B00000 For Additional Cooling
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220

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824302B00000 - Rev B